



11-26-02

2826

Express Mail No.: EL 500 577 018 US

\$

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Cheah *et al.*

Application No.: 10/068,523

Group Art Unit: 2826

Filed: February 5, 2002

Examiner: Alexander O. Williams

For: THERMALLY
ENHANCED METAL
CAPPED BGA PACKAGE

Attorney Docket No.: 9818-066-999

#10
Amata
OSmales
12/22/03

RESPONSE TO THE FIRST OFFICE ACTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated August 8, 2002, entry of the following amendments and remarks is respectfully requested.

AMENDMENT

IN THE CLAIMS:

Please cancel claims 2 through 5 without prejudice.

A marked up version of the revised claim, showing insertions and deletions, is included in the Appendix attached hereto.

Please rewrite the pending claims as follows:

RECEIVED
DEC - 3 2002
TECHNOLOGY CENTER 2800

- A'
- 1 1. (Amended) A ball-grid array package comprising:
 - 2 a substrate having first and second sides;
 - 3 an integrated circuit device attached to said first side of said substrate;
 - 4 a metal cap having a side wall portion and a top portion forming an internal
 - 5 cavity, wherein said metal cap is attached to said first side of said substrate along a peripheral